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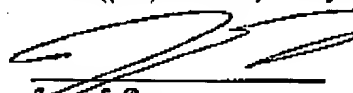
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicants : Davlin et al.
Serial No. : 09/651,498
Filed : August 30, 2000
Title : Temperature Control Elements, Spindle Assembly, and Wafer
Processing Assembly Incorporating the Same
Docket No. : MIO 0071 PA
Examiner : Ram N. Kackar
Art Unit : 1763
Confirm. No. : 1401

Assistant Commissioner for Patents
Washington, D.C. 20231

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AMENDMENT

This paper is being filed in response to the Office Action of May 16, 2003.
Reconsideration of the present application is respectfully requested in light of the
amendments and remarks below, which include, in order of appearance, beginning on
separate sheets:

- Amendments to the Specification;
- Amendments to the Claims;
- Amendments to the Drawings; and
- Remarks.